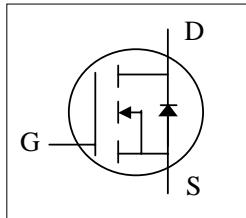




- ▼ Low On-resistance
- ▼ Single Drive Requirement
- ▼ Surface Mount Package

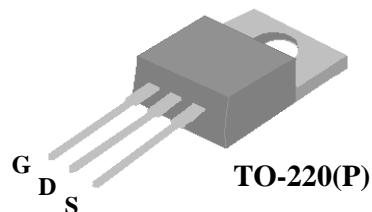
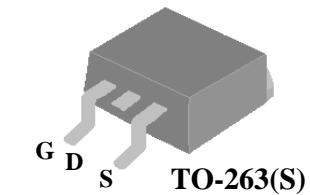


$BV_{DSS}$	60V
$R_{DS(ON)}$	36mΩ
$I_D$	25A

### Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-263 package is widely preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP9971GP) are available for low-profile applications.



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	25	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	16	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	80	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation	39	W
	Linear Derating Factor	0.31	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	3.2	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient (PCB mount) <sup>3</sup>	40	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	62	°C/W



### Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	60	-	-	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=18\text{A}$	-	-	36	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=12\text{A}$	-	-	50	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=250\mu\text{A}$	1	-	3	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=18\text{A}$	-	17	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=18\text{A}$	-	18	30	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	6	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge		-	11	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=30\text{V}$	-	9	-	ns
$t_r$	Rise Time	$I_{\text{D}}=18\text{A}$	-	24	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	26	-	ns
$t_f$	Fall Time		-	7	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	1700	2700	pF
$C_{\text{oss}}$	Output Capacitance		-	160	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	110	-	pF

### Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=25\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_{\text{S}}=18\text{A}$ , $V_{\text{GS}}=0\text{V}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	37	-	ns
			-	38	-	nC

### Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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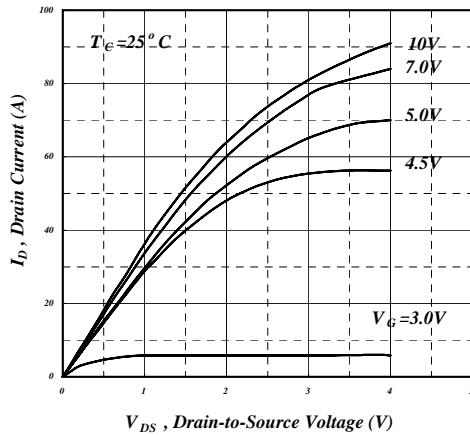


Fig 1. Typical Output Characteristics

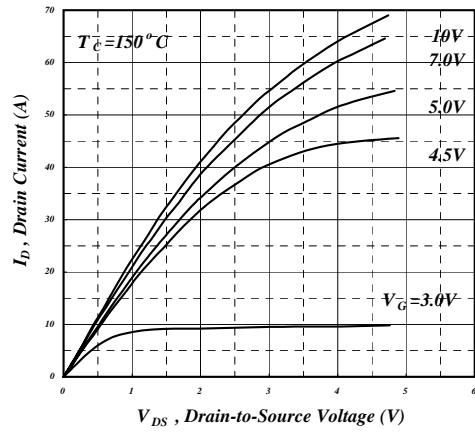


Fig 2. Typical Output Characteristics

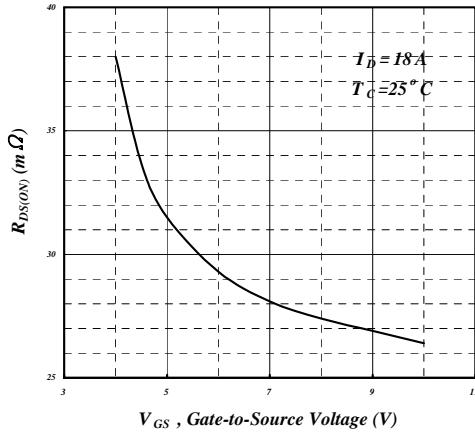


Fig 3. On-Resistance v.s. Gate Voltage

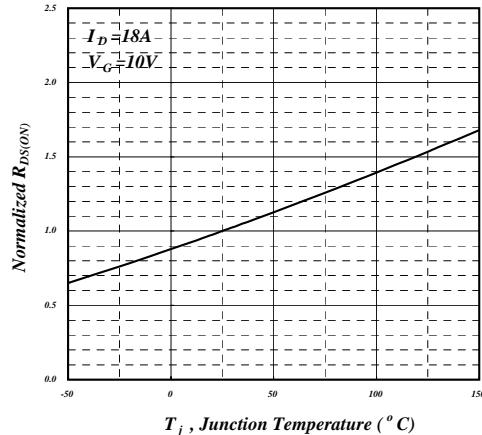


Fig 4. Normalized On-Resistance v.s. Junction Temperature

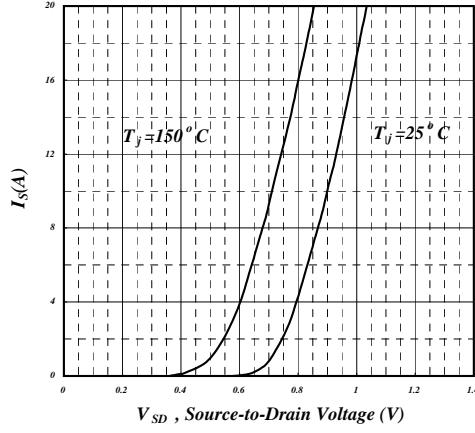


Fig 5. Forward Characteristic of Reverse Diode

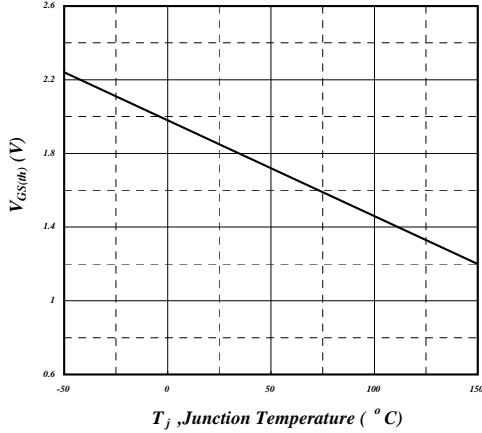
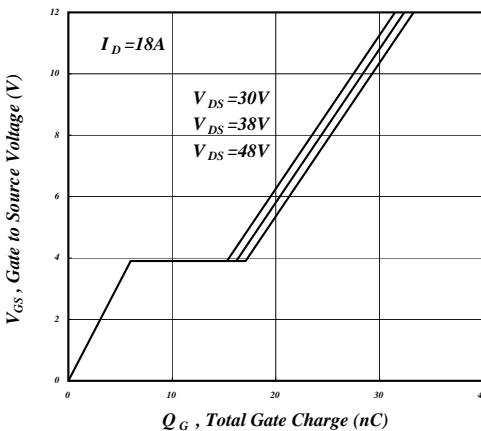
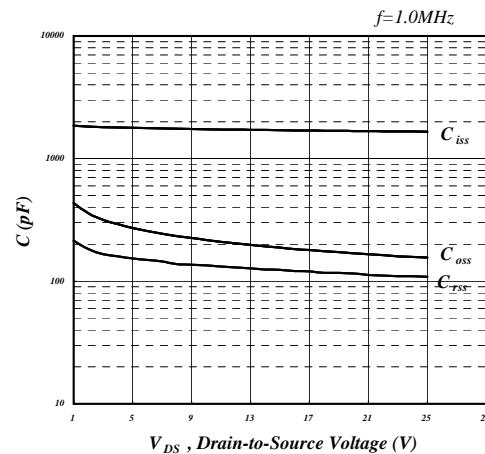


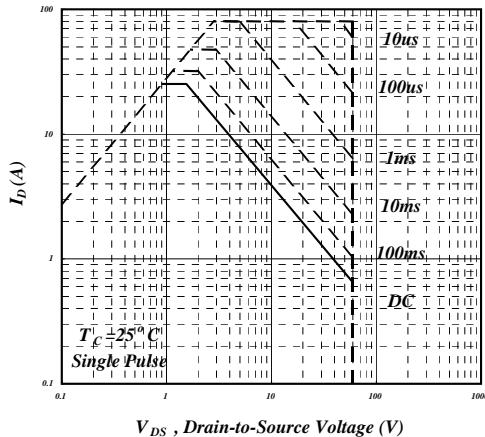
Fig 6. Gate Threshold Voltage v.s. Junction Temperature



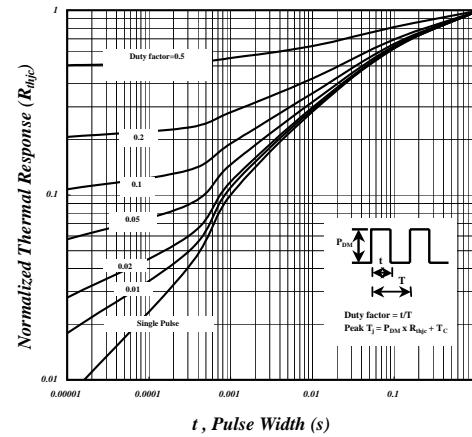
**Fig 7. Gate Charge Characteristics**



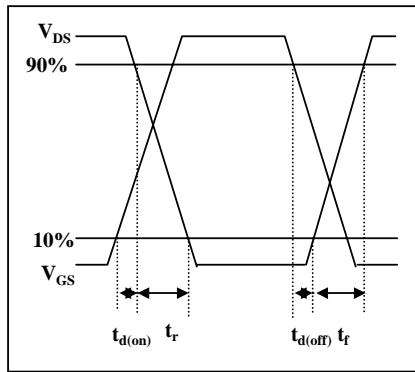
**Fig 8. Typical Capacitance Characteristics**



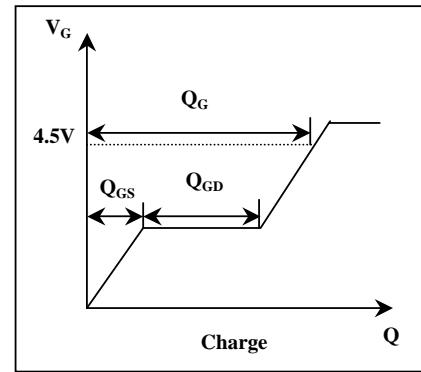
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Switching Time Waveform**



**Fig 12. Gate Charge Waveform**